

[54] INTEGRATED CIRCUIT CHIP CARRIER

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[73] Assignee: Westinghouse Electric Corp., Pittsburgh, Pa.

[**] Term: 14 Years

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[58] Field of Search D13/40, 41, 99, 184, D13/199; D8/354, 384; D9/424, 499; 361/403, 389; 324/158 F; 206/328-331

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[57] CLAIM

The ornamental design for an integrated circuit chip carrier, as shown and described.

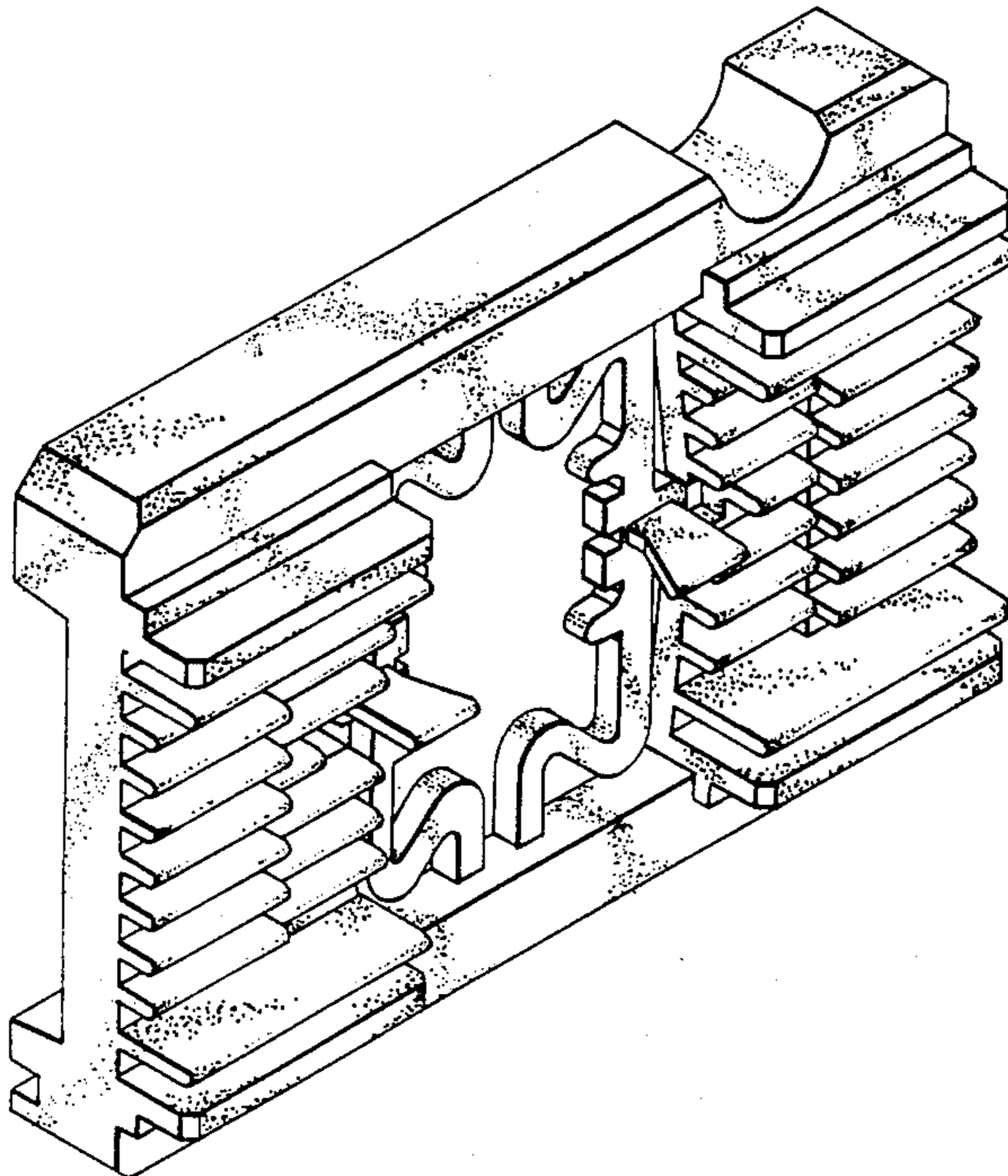
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DESCRIPTION

FIG. 1 is a perspective view of an integrated circuit chip carrier showing my new design; FIG. 2 is a top plan view thereof; FIG. 3 is a bottom plan view thereof; FIG. 4 is an end elevational view thereof; and FIG. 5 is a side elevational view thereof, the opposite side elevational view being a mirror image.



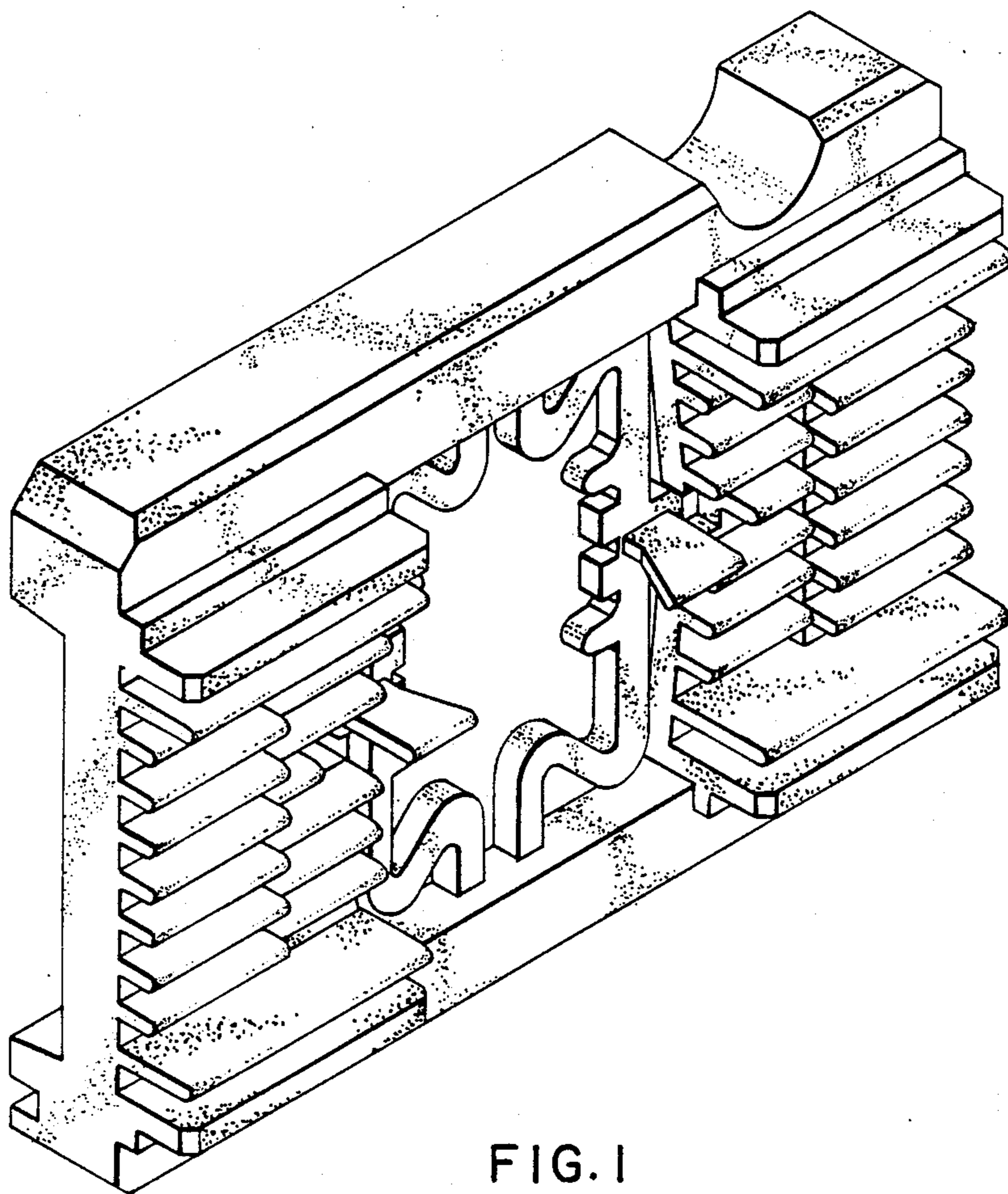


FIG. 1

FIG. 2

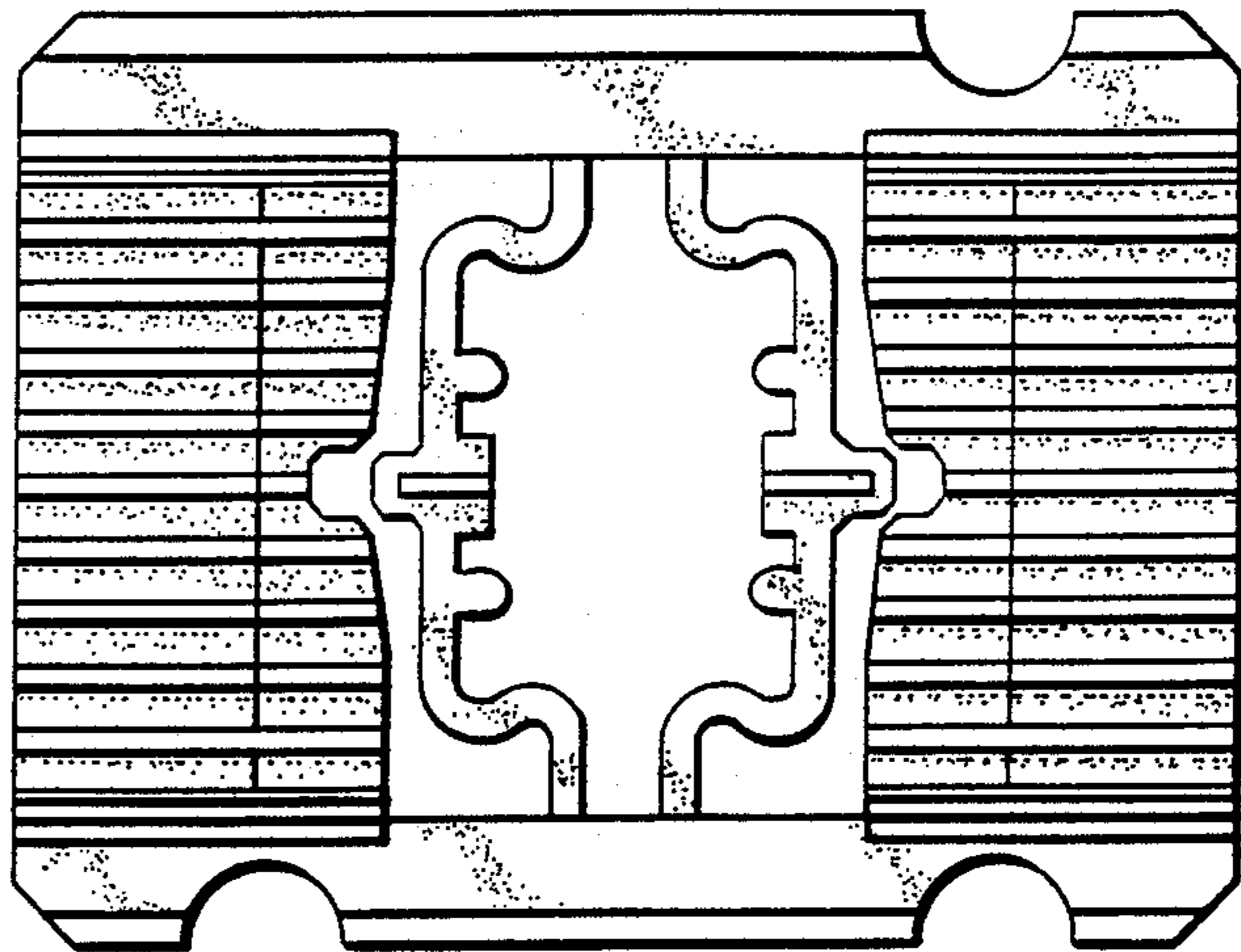


FIG. 5

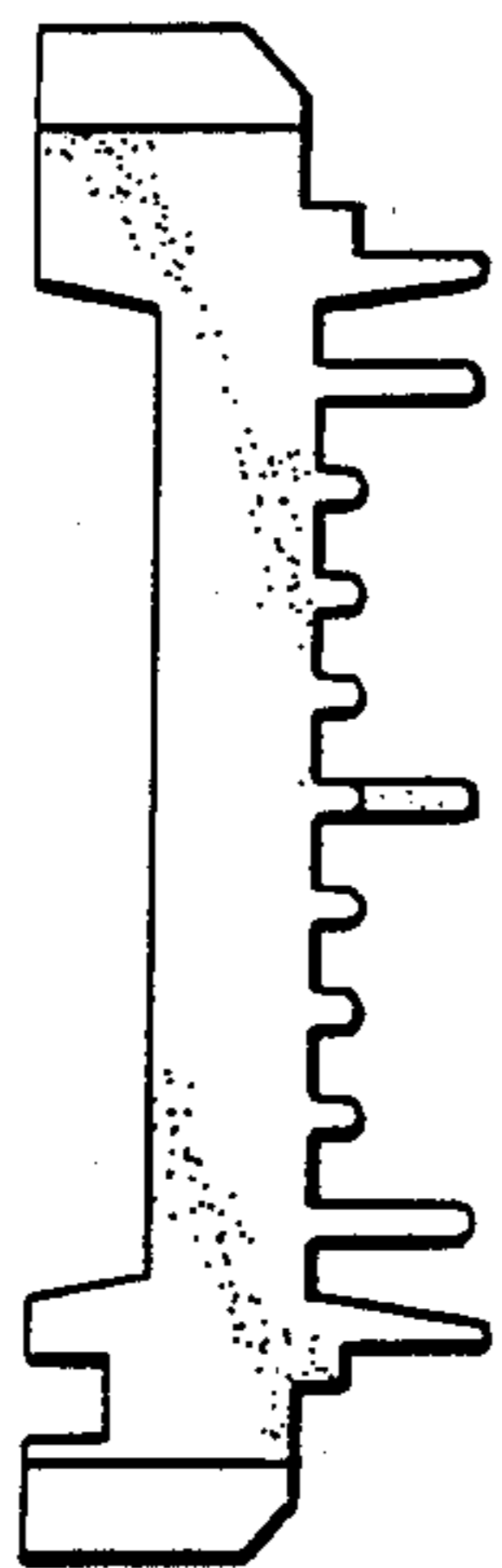


FIG. 4



FIG. 3

